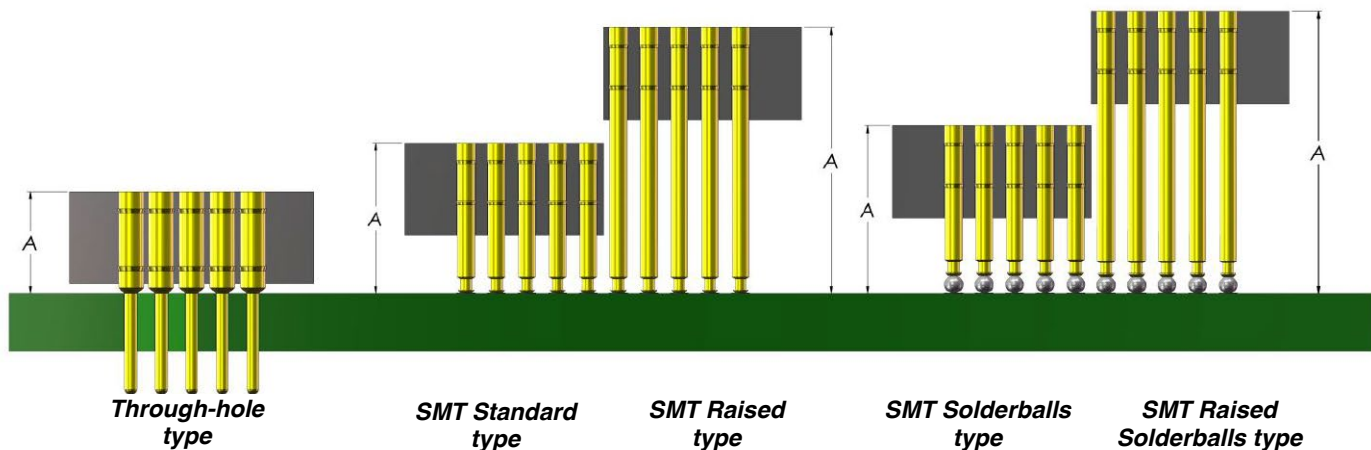
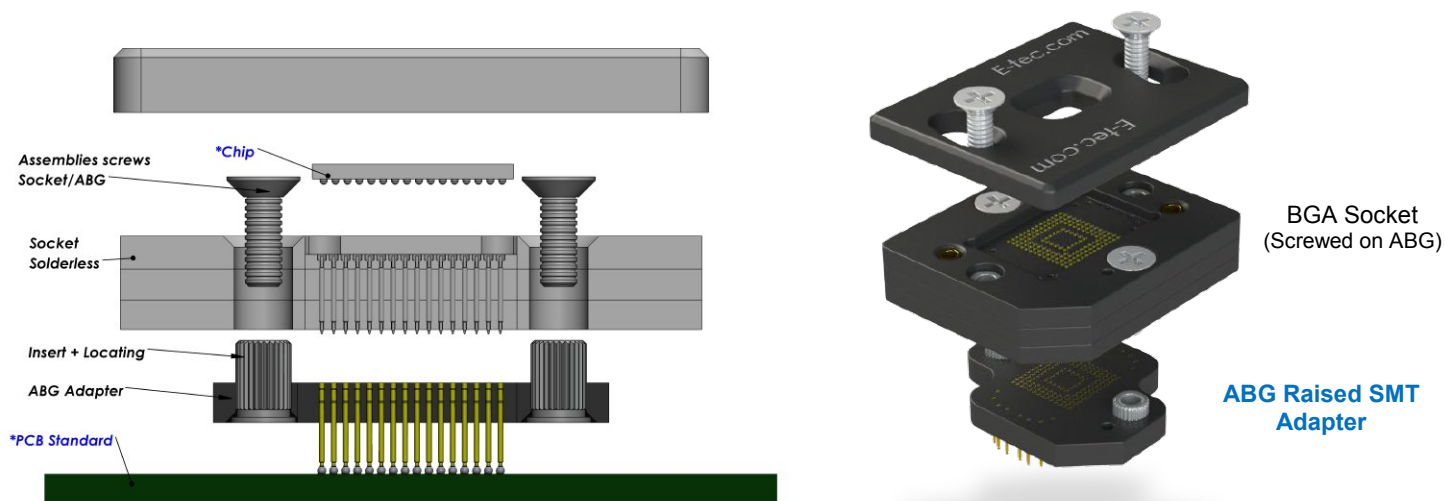


ABG adapter to be soldered onto board



Specifications				
Terminal Type 116, 158, 168, 175, 420, 406, & 437	Material Contact : CuZn Solderball : SAC305	Plating Au over Ni over Cu	Adapter Material: Polyepoxy or other high temp mat.	Others Operating Temperature : -55°C to +125°C Processing Temperature : +260°C for 60 sec.

How to order

ABG ### - ### - ### # 5 ##

Nbr of contacts Depends on ballcount of chip	Contact type E116 : Through-hole for 1.27 mm pitch (concave) A=2.0mm E158 : Through-hole Optional for 1.27 mm pitch A=2.0 mm E168 : Through-hole for 1.00 mm pitch A= 2.5 mm E175 : Through-hole for 0.80 mm pitch A= 2.5 mm E420 : Through-hole for 0.60 mm pitch A= 1.5 mm E406 : SMT 0.40 / 0.50 / 0.60 mm pitch A= 2.8 mm E437 : Raised SMT 0.40 / 0.50 / 0.60 mm pitch A= 4.7 mm SB406 : SMT Solderballs 0.40 / 0.50 / 0.60 mm pitch A= 2.8 mm SB437 : Raised SMT Solderballs 0.40 / 0.50 / 0.60 mm A= 4.7 mm	Plating 55: Gold/Gold For Solderballs only : 95: Tin/Gold 05: PbTin/Gold	Pitch 12: 1.27 mm 10: 1.0 mm (up to 1.26) 08: 0.8 mm (up to 0.99) 07: 0.70 mm (up to 0.79) 06: 0.60 mm (up to 0.69) 05: 0.50 mm (up to 0.59) 04: 0.40 mm (up to 0.49)
	Grid code / Config. code Will be given by the factory after receipt of the chip datasheet		